

**Description**

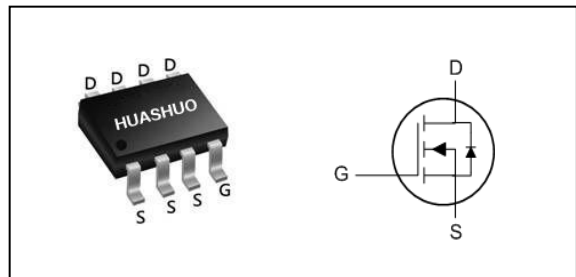
The HSM6048 is the high cell density SGT N-ch MOSFETs, which provide excellent R<sub>DS(ON)</sub> and gate charge for most of the synchronous buck converter applications.

The HSM6048 meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

- Super Low Gate Charge
- 100% EAS Guaranteed
- Green Device Available
- Excellent CdV/dt effect decline
- Advanced high cell density Trench technology

**Product Summary**

|                         |     |    |
|-------------------------|-----|----|
| V <sub>DS</sub>         | 60  | V  |
| R <sub>DS(ON),max</sub> | 3.6 | mΩ |
| I <sub>D</sub>          | 16  | A  |

**SOP-8 Pin Configuration**

**Absolute Maximum Ratings**

| Symbol                               | Parameter                                  | Rating     | Units |
|--------------------------------------|--|------------|-------|
| V <sub>DS</sub>                      | Drain-Source Voltage                       | 60         | V     |
| V <sub>GS</sub>                      | Gate-Source Voltage                        | ±20        | V     |
| I <sub>D</sub> @T <sub>A</sub> =25°C | Continuous Drain Current <sup>1,6</sup>    | 16         | A     |
| I <sub>D</sub> @T <sub>A</sub> =70°C | Continuous Drain Current <sup>1,6</sup>    | 12.8       | A     |
| I <sub>DM</sub>                      | Pulsed Drain Current <sup>2</sup>          | 64         | A     |
| EAS                                  | Single Pulse Avalanche Energy <sup>3</sup> | 101        | mJ    |
| I <sub>AS</sub>                      | Avalanche Current                          | 45         | A     |
| P <sub>D</sub> @T <sub>A</sub> =25°C | Total Power Dissipation <sup>4</sup>       | 1.67       | W     |
| T <sub>STG</sub>                     | Storage Temperature Range                  | -55 to 150 | °C    |
| T <sub>J</sub>                       | Operating Junction Temperature Range       | -55 to 150 | °C    |

**Thermal Data**

| Symbol           | Parameter  | Typ. | Max. | Unit |
|------------------|--|------|------|------|
| R <sub>θJA</sub> | Thermal Resistance Junction-Ambient <sup>1</sup> | ---  | 75   | °C/W |
| R <sub>θJC</sub> | Thermal Resistance Junction-Case <sup>1</sup>    | ---  | 24   | °C/W |

**Electrical Characteristics ( $T_J=25\text{ }^\circ\text{C}$ , unless otherwise noted)**

| Symbol       | Parameter                                      | Conditions                                     | Min. | Typ. | Max.      | Unit      |
|--------------|--|--|------|------|-----------|-----------|
| $BV_{DSS}$   | Drain-Source Breakdown Voltage                 | $V_{GS}=0V, I_D=250\mu A$                      | 60   | ---  | ---       | V         |
| $R_{DS(ON)}$ | Static Drain-Source On-Resistance <sup>2</sup> | $V_{GS}=10V, I_D=15A$                          | ---  | 3.2  | 3.6       | $m\Omega$ |
|              |  | $V_{GS}=4.5V, I_D=15A$                         | ---  | 4.5  | 5.4       | $m\Omega$ |
| $V_{GS(th)}$ | Gate Threshold Voltage                         | $V_{GS}=V_{DS}, I_D=250\mu A$                  | 1.2  | ---  | 2.3       | V         |
| $I_{DSS}$    | Drain-Source Leakage Current                   | $V_{DS}=48V, V_{GS}=0V, T_J=25^\circ C$        | ---  | ---  | 1         | $\mu A$   |
|              |  | $V_{DS}=48V, V_{GS}=0V, T_J=55^\circ C$        | ---  | ---  | 5         | $\mu A$   |
| $I_{GSS}$    | Gate-Source Leakage Current                    | $V_{GS}=\pm 20V, V_{DS}=0V$                    | ---  | ---  | $\pm 100$ | nA        |
| $g_{fs}$     | Forward Transconductance                       | $V_{DS}=5V, I_D=15A$                           | ---  | 65   | ---       | S         |
| $R_g$        | Gate Resistance                                | $V_{DS}=0V, V_{GS}=0V, f=1MHz$                 | ---  | 0.7  | ---       | $\Omega$  |
| $Q_g$        | Total Gate Charge (10V)                        | $V_{DS}=30V, V_{GS}=10V, I_D=15A$              | ---  | 58   | ---       | nC        |
| $Q_{gs}$     | Gate-Source Charge                             |  | ---  | 16   | ---       |           |
| $Q_{gd}$     | Gate-Drain Charge                              |  | ---  | 4    | ---       |           |
| $T_{d(on)}$  | Turn-On Delay Time                             | $V_{DD}=30V, V_{GS}=10V, R_G=3\Omega, I_D=15A$ | ---  | 18   | ---       | ns        |
| $T_r$        | Rise Time                                      |  | ---  | 8    | ---       |           |
| $T_{d(off)}$ | Turn-Off Delay Time                            |  | ---  | 50   | ---       |           |
| $T_f$        | Fall Time                                      |  | ---  | 10.5 | ---       |           |
| $C_{iss}$    | Input Capacitance                              | $V_{DS}=30V, V_{GS}=0V, f=1MHz$                | ---  | 3458 | ---       | pF        |
| $C_{oss}$    | Output Capacitance                             |  | ---  | 1522 | ---       |           |
| $C_{rss}$    | Reverse Transfer Capacitance                   |  | ---  | 22   | ---       |           |

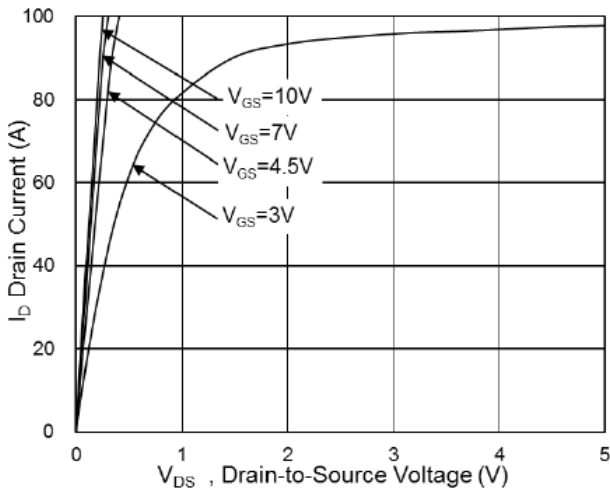
**Diode Characteristics**

| Symbol   | Parameter                                | Conditions                                  | Min. | Typ. | Max. | Unit |
|----------|--|---|------|------|------|------|
| $I_S$    | Continuous Source Current <sup>1,5</sup> | $V_G=V_D=0V$ , Force Current                | ---  | ---  | 16   | A    |
| $V_{SD}$ | Diode Forward Voltage <sup>2</sup>       | $V_{GS}=0V, I_S=1A, T_J=25^\circ C$         | ---  | ---  | 1.2  | V    |
| $t_{rr}$ | Reverse Recovery Time                    | $I_F=15A, di/dt=100A/\mu s, T_J=25^\circ C$ | ---  | 24   | ---  | nS   |
| $Q_{rr}$ | Reverse Recovery Charge                  |   | ---  | 85   | ---  | nC   |

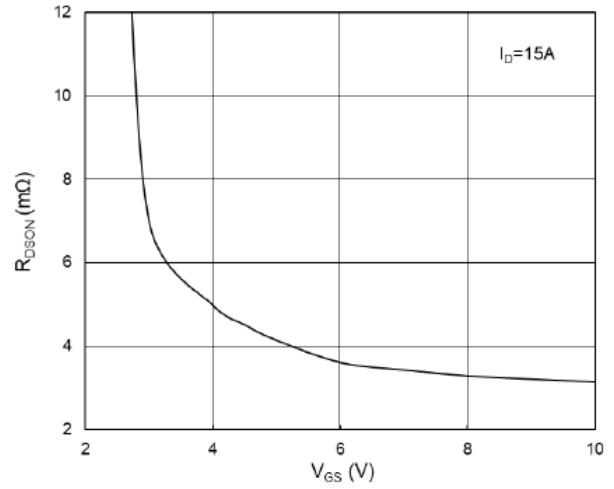
Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq 300\mu s$  , duty cycle  $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is  $V_{DD}=50V, V_{GS}=10V, L=0.1mH, I_{AS}=45A$
- 4.The power dissipation is limited by 150 $^\circ C$  junction temperature
- 5.The data is theoretically the same as  $I_D$  and  $I_{DM}$  , in real applications , should be limited by total power dissipation.
- 6.The maximum current rating is package limited.

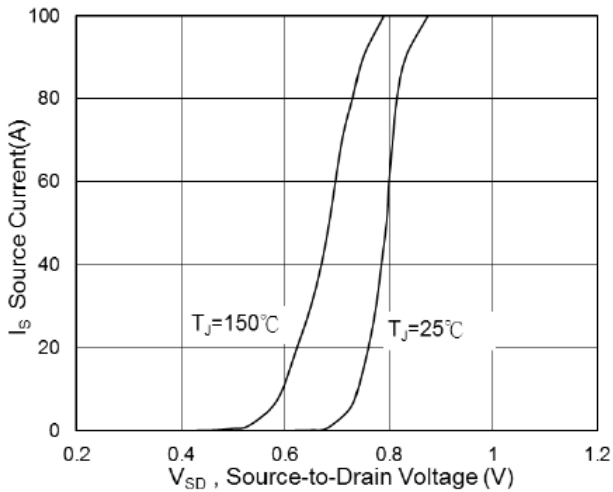
**Typical Characteristics**



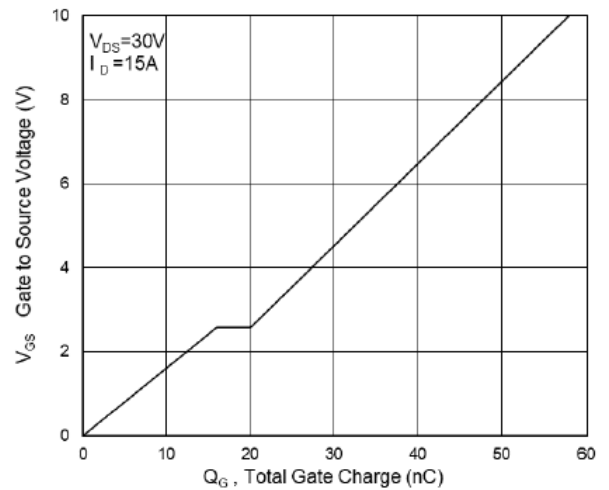
**Fig.1 Typical Output Characteristics**



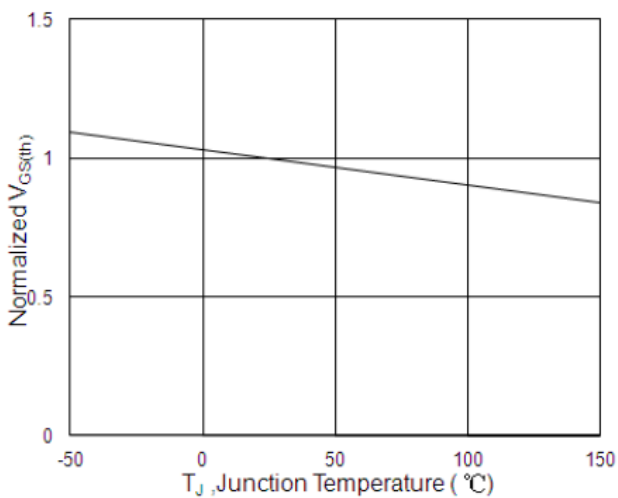
**Fig.2 On-Resistance vs G-S Voltage**



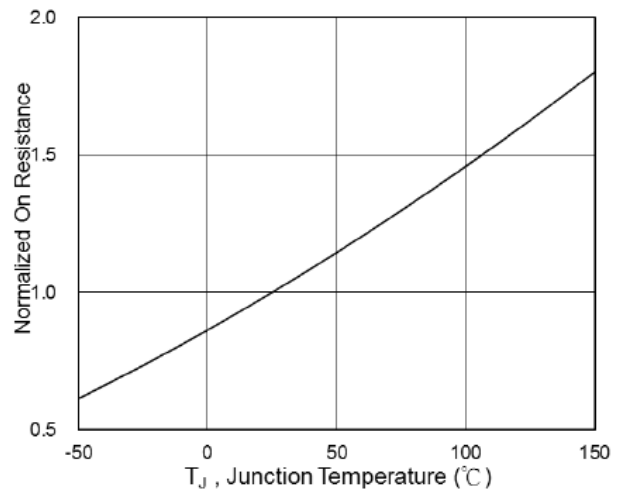
**Fig.3 Diode Forward Voltage vs. Current**



**Fig.4 Gate-Charge Characteristics**

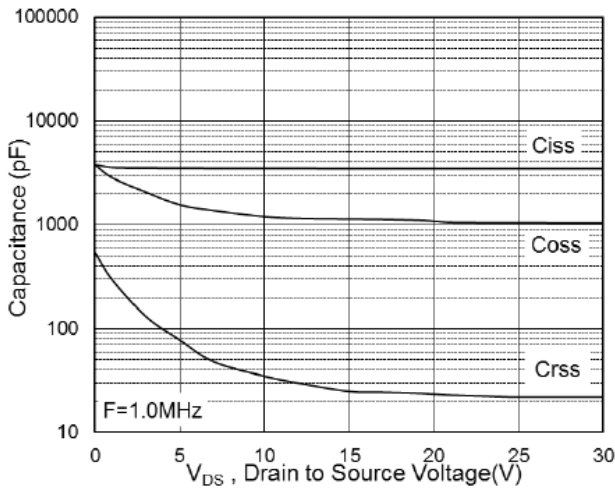


**Fig.5 Normalized  $V_{GS(th)}$  vs  $T_J$**

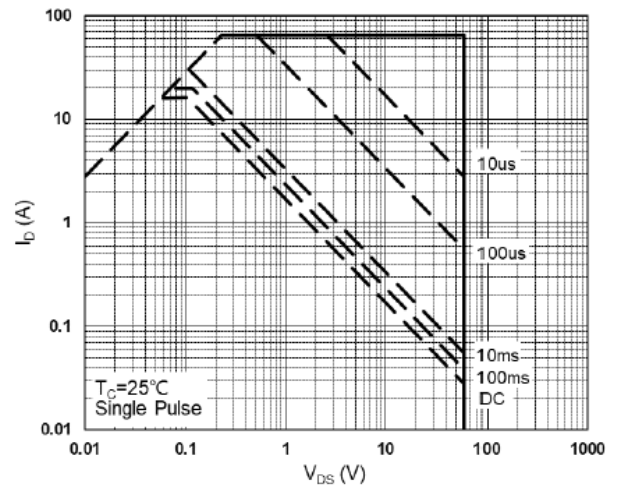


**Fig.6 Normalized  $R_{DS(on)}$  vs  $T_J$**

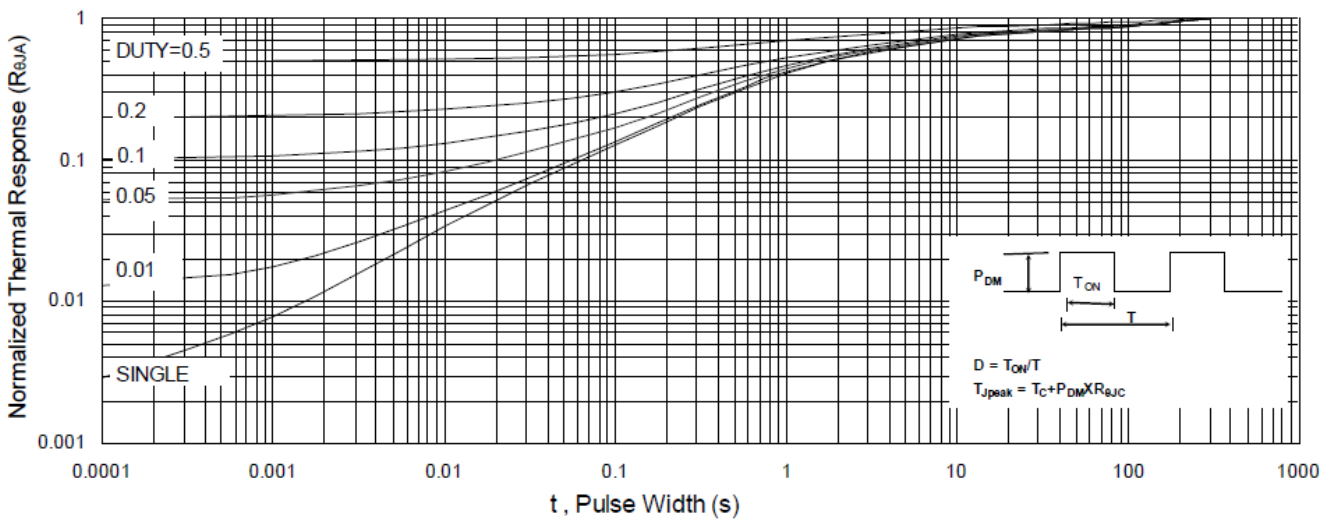
**N-Ch 60V Fast Switching MOSFETs**



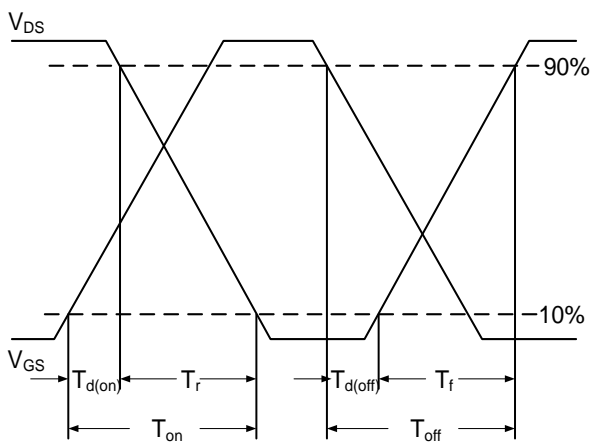
**Fig.7 Capacitance**



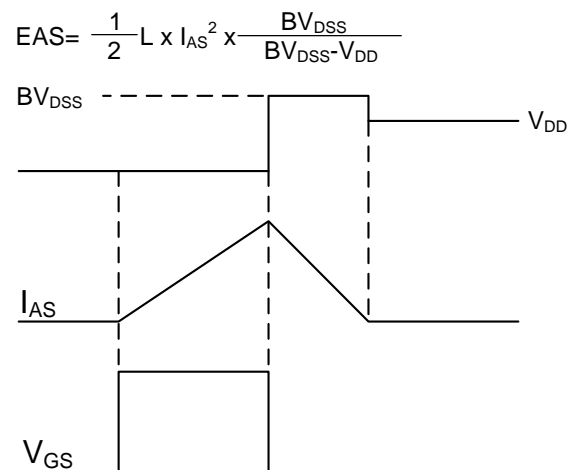
**Fig.8 Safe Operating Area**



**Fig.9 Normalized Maximum Transient Thermal Impedance**



**Fig.10 Switching Time Waveform**



**Fig.11 Unclamped Inductive Switching**

## Ordering Information

| Part Number | Package code | Packaging      |
|-------------|--------------|----------------|
| HSM6048     | SOP-8        | 2500/Tape&Reel |

